Product Information Sheet

EPO-TEK® B9126-8

Date:	September 2017	**Recommended Cure: 150°C / 1 Hour**
Rev:	III	
No. of Components:	Single	Minimum Alternative Cure(s):
Mix Ratio by Weight:	N/A	*May not achieve performance properties listed below*
Specific Gravity:	2.92	150°C / 5 Minutes
Pot Life:	5 Days	120°C / 15 Minutes
Shelf Life- Bulk:	One year refrigerated	

NOTES:

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.

Product Description: A single component, thermally and electrically conductive, epoxy adhesive designed for semiconductor die attach and circuit assembly applications. Its unique features are a pot-life of several days, low temperature cure and syringe dispensing rheology. It can be used for electrical connections when bonding chips, SMDs, PCBs and substrates.

Typical Properties: Cure condition: 150°C / 1 Hour Different batches, conditions & applications yield differing results.
Data below is not guaranteed. To be used as a guide only, not as a specification. * denotes test on lot acceptance basis

PHYSICAL PROPERTIES:				
* Color (before cure):	Silver			
* Consistency:	Smooth paste			
* Viscosity (23°C) @ 20 rpm:		11,000-18,500	cPs	
Thixotropic Index:		3.2		
* Glass Transition Temp:		≥ 60	°C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)	
Coefficient of Thermal Expansion (CTE):				
Below Tg:		Upon request		
Above Tg:		Upon request		
Shore D Hardness:		71		
Lap Shear @ 23°C:		980	psi	
Die Shear @ 23°C:		≥ 5	Kg	1,778 psi
Degradation Temp:		340	°C	
Weight Loss:				
@ 300°C:		1.07	%	
Suggested Operating Temperature:		< 275	°C (Intermittent)	
Storage Modulus:		227,897	psi	
Ion Content:	Cl^-:	80 ppm	Na^+:	23 ppm
	NH_4^+:	41 ppm	K^+:	8 ppm
* Particle Size:		≤ 30	microns	

ELECTRICAL AND THERMAL PROPERTIES:		
Thermal Conductivity:	1.2	W/mK
* Volume Resistivity @ 23°C:	≤ 0.0002	Ohm-cm

This information is based on data and tests believed to be accurate. Epoxy Technology, Inc. makes no warranties (expressed or implied) as to its accuracy and assumes no liability in connection with any use of this product.

EPOXY TECHNOLOGY, INC.
14 FORTUNE DRIVE, BILLERICA, MA 01821 (978) 667-3805, FAX (978) 663-9782
www.epotek.com